

METHOD OF MANUFACTURE OF SILICON BASED PACKAGE AND  
DEVICE MANUFACTURED THEREBY

ABSTRACT OF THE DISCLOSURE

5 A silicon based package (SBP) is formed starting with a thick wafer, which serves as the  
base for the SBP, composed of silicon which has a first surface and a reverse surface  
which are planar. Then form an interconnection structure including multilayer conductor  
patterns over the first surface. Form a temporary bond between the SBP and a wafer  
holder, with the wafer holder being a rigid structure. Thin the wafer to a desired thickness  
to form an Ultra Thin Silicon Wafer (UTSW) for the SBP. Forming via holes which  
10 extend through the UTSW, forming metallization in the via holes which extends through  
the UTSW, making electrical contact to the interconnection structure on the first surface.  
Then bond the metallization in the via holes to pads of a carrier.